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**ON Semiconductor®** 

# FDS6975 Dual P-Channel, Logic Level, PowerTrench<sup>™</sup> MOSFET

### **General Description**

These P-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for notebook computer applications: load switching and power management, battery charging circuits, and DC/DC conversion.

## Features

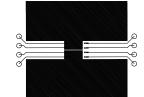
- $\begin{array}{c|c} \bullet & -6 \mbox{ A, -30 V. } R_{\rm DS(ON)} = 0.032 \ \Omega & @ \mbox{ V}_{\rm GS} = -10 \ V, \\ R_{\rm DS(ON)} = 0.045 \ \Omega & @ \mbox{ V}_{\rm GS} = -4.5 \ V. \end{array}$
- Low gate charge (14.5nC typical).
- High performance trench technology for extremely low R<sub>DS(ON)</sub>.
- High power and current handling capability.

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SOT	-23 SuperSOT <sup>™</sup> -6	SuperSOT <sup>™</sup> -8	SO-8	SOT-223	SOIC-16
	D1 D2 FD5	S2 G2	[ [ [		4 3 2 1
bcol	Ito Movimum Potingo		ing worked		
	ute Maximum Ratings	$T_A = 25^{\circ}C$ unless otherw	ise noted	Ratings	Units
mbol		$T_A = 25^{\circ}C$ unless otherw	ise noted	Ratings -30	Units V
r <b>mbol</b> ss	Parameter	T <sub>A</sub> = 25°C unless otherw	ise noted		
<b>mbol</b>	Parameter Drain-Source Voltage	T <sub>A</sub> = 25°C unless otherw (Note 1a)	ise noted	-30	V
<b>mbol</b>	Parameter       Drain-Source Voltage       Gate-Source Voltage		ise noted	-30 ±20	V
rmbol ss ss	Parameter       Drain-Source Voltage       Gate-Source Voltage       Drain Current - Continuous	(Note 1a)	ise noted	-30 +20 -6	V
<b>rmbol</b> ISS ISS	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed	(Note 1a)	ise noted	-30 ±20 -6 -20	V V A
<b>rmbol</b> ISS ISS	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed         Power Dissipation for Dual Operation	(Note 1a)	ise noted	-30 ±20 -6 -20 2	V V A
<b>rmbol</b> ISS ISS	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed         Power Dissipation for Dual Operation	(Note 1a) ation Pration (Note 1a)		-30 +20 -6 -20 2 1.6	V V A
ymbol DSS DSS D	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed         Power Dissipation for Dual Operation	(Note 1a) ation station (Note 1a) (Note 1b) (Note 1c)	ise noted	-30 ±20 -6 -20 2 1.6 1	V V A
rmbol sss sss T <sub>STG</sub>	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed         Power Dissipation for Dual Opera         Power Dissipation for Single Opera	(Note 1a) ation station (Note 1a) (Note 1b) (Note 1c)	ise noted	-30 +20 -6 -20 2 1.6 1 0.9	V V A W
ymbol DISS	Parameter         Drain-Source Voltage         Gate-Source Voltage         Drain Current - Continuous         - Pulsed         Power Dissipation for Dual Opera         Power Dissipation for Single Ope         Operating and Storage Tempera	(Note 1a) ation rration (Note 1a) (Note 1b) (Note 1c) ture Range		-30 +20 -6 -20 2 1.6 1 0.9	V V A W

Symbol	Parameter	Conditions	Min	Тур	Max	Units
OFF CHAR	ACTERISTICS	· ·	•		•	•
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_{D} = -250 \mu A$	-30			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_D$ = -250 µA, Referenced to 25 °C		-21		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{\rm DS} = -24  \text{V},  V_{\rm GS} = 0  \text{V}$			-1	μA
		T <sub>J</sub> = 55°C			-10	μA
	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			100	nA
	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
ON CHARA	CTERISTICS (Note 2)			•		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-1.7	-3	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate Threshold Voltage Temp. Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25 ^{\circ}\text{C}$		4		mV/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -6 \text{ A}$		0.025	0.032	Ω
		T <sub>J</sub> =125°C		0.033	0.051	
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5 \text{ A}$		0.034	0.045	
I <sub>D(ON)</sub>	On-State Drain Current	$V_{GS} = -10 \text{ V}, V_{DS} = -5 \text{ V}$	-20			Α
9 <sub>FS</sub>	Forward Transconductance	$V_{\rm DS} = -10 \text{ V}, \ I_{\rm D} = -6 \text{ A}$		16		S
DYNAMIC C	HARACTERISTICS	·		•		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -15 V, V_{GS} = 0 V,$ f = 1.0 MHz		1540		pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		400		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			170		pF
SWITCHING	CHARACTERISTICS (Note 2)					
t <sub>D(on)</sub>	Turn - On Delay Time	$V_{DS}$ = -15 V, I <sub>D</sub> = -1 A		13	24	ns
t,	Turn - On Rise Time	$V_{\text{GEN}}$ = -10 V, $R_{\text{GEN}}$ = 6 $\Omega$		22	35	ns
t <sub>D(off)</sub>	Turn - Off Delay Time			47	75	ns
t,	Turn - Off Fall Time			18	30	ns
Q <sub>g</sub>	Total Gate Charge	$V_{\rm DS} = -10 \text{ V}, \ I_{\rm D} = -6 \text{ A},$		14.5	20	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -5 V		4		nC
Q <sub>gd</sub>	Gate-Drain Charge			5		nC
DRAIN-SOU	RCE DIODE CHARACTERISTICS AND MAXIM	UM RATINGS	·	·		·
I <sub>s</sub>	Maximum Continuous Drain-Source Diode Fo			-1.3	А	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = -1.3 A$ (Note 2)		-0.73	-1.2	V

Notes:

1. R<sub>g,A</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>g,c</sub> is guaranteed by design while R<sub>gCA</sub> is determined by the user's board design.

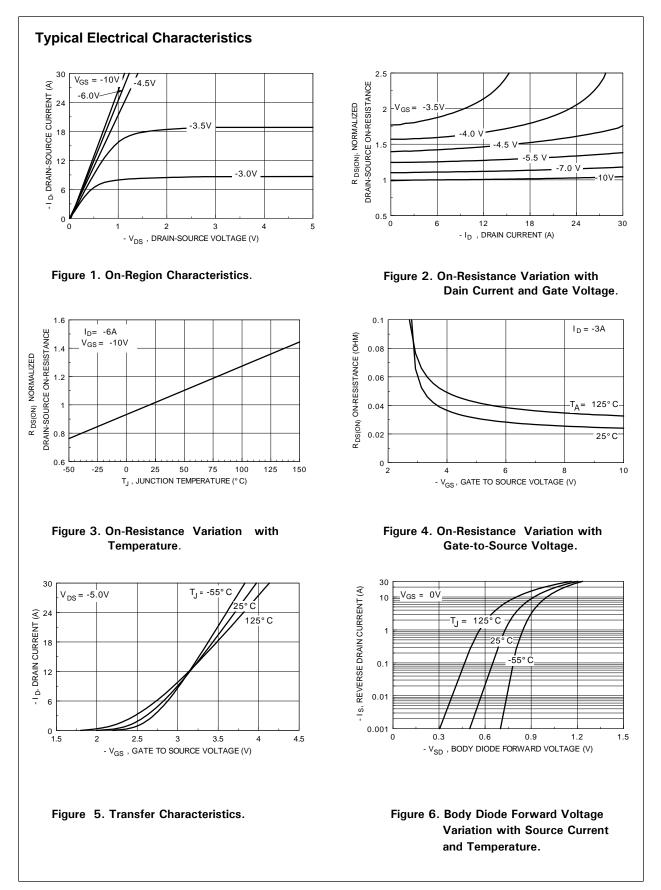


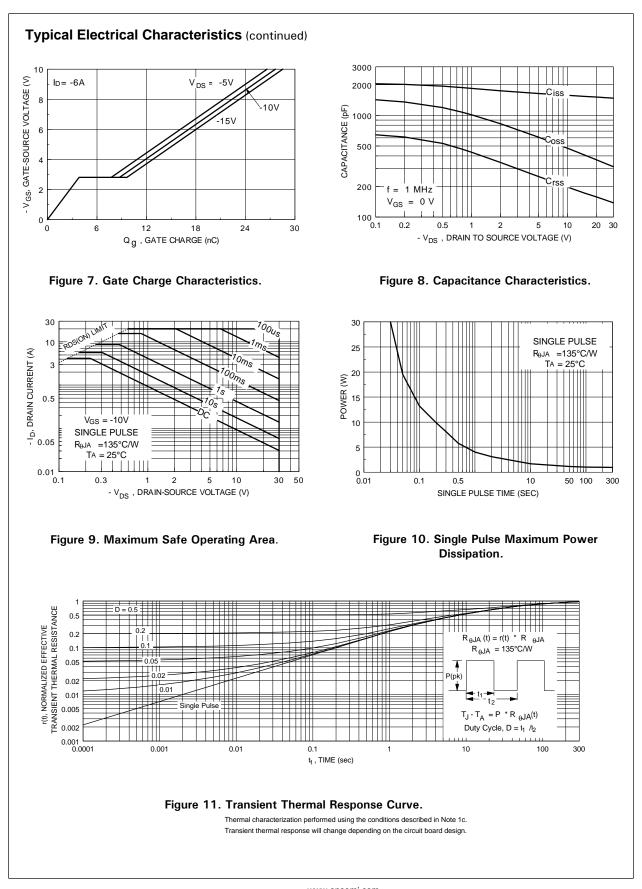


b. 125°C/W on a 0.02 in<sup>2</sup> pad of 2oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width  $\leq$  300 $\!\mu\text{s},$  Duty Cycle  $\leq$  2.0%.





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